

# TQP7M9102

## ½W High Linearity Amplifier



### Applications

- Repeaters
- Mobile Infrastructure
- CDMA / WCDMA / LTE
- General Purpose Wireless

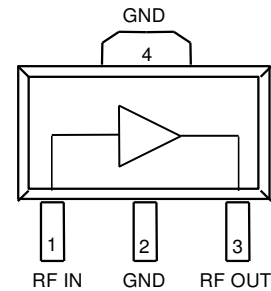


3-pin SOT-89 Package

### Product Features

- 400-4000 MHz
- +27.5 dBm P1dB
- +44 dBm Output IP3
- 17.8 dB Gain @ 2140 MHz
- +5V Single Supply, 135 mA Current
- Internal RF overdrive protection
- Internal DC overvoltage protection
- On chip ESD protection
- SOT-89 Package

### Functional Block Diagram



### General Description

The TQP7M9102 is a high linearity driver amplifier in a low-cost, RoHS compliant, surface mount package. This InGaP/GaAs HBT delivers high performance across a broad range of frequencies with +44 dBm OIP3 and +27.5 dBm P1dB while only consuming 135 mA quiescent current. All devices are 100% RF and DC tested.

The TQP7M9102 incorporates on-chip features that differentiate it from other products in the market. The amplifier integrates an on-chip DC over-voltage and RF over-drive protection. This protects the amplifier from electrical DC voltage surges and high input RF input power levels that may occur in a system. On-chip ESD protection allows the amplifier to have a very robust Class 2 HBM ESD rating.

The TQP7M9102 is targeted for use as a driver amplifier in wireless infrastructure where high linearity, medium power, and high efficiency are required. The device is an excellent candidate for transceiver line cards in current and next generation multi-carrier 3G / 4G base stations.

### Pin Configuration

Pin #	Symbol
1	RF Input
3	RF Output / Vcc
2, 4	Ground

### Ordering Information

Part No.	Description
TQP7M9102	0.5 W High Linearity Amplifier
TQP7M9102-PCB900	TQP7M9102 869-960MHz EVB
TQP7M9102-PCB2140	TQP7M9102 2.11-2.17GHz EVB

Standard T/R size = 1000 pieces on a 7" reel.

# TQP7M9102

## ½W High Linearity Amplifier



### Specifications

#### Absolute Maximum Ratings

Parameter	Rating
Storage Temperature	-65 to +150 °C
Device Voltage, V <sub>cc</sub>	+8 V
Maximum Input Power, CW	+27 dBm

Operation of this device outside the parameter ranges given above may cause permanent damage.

#### Recommended Operating Conditions

Parameter	Min	Typ	Max	Units
V <sub>cc</sub>	+4.75	+5	+5.25	V
T <sub>case</sub>	-40		85	°C
T <sub>j</sub> (for >10 <sup>6</sup> hours MTTF)			160	°C

Electrical specifications are measured at specified test conditions. Specifications are not guaranteed over all recommended operating conditions.

#### Electrical Specifications

Test conditions unless otherwise noted: +25°C, +5V V<sub>supply</sub>, 50 Ω system, tuned application circuit

Parameter	Conditions	Min	Typical	Max	Units
Operational Frequency Range		400		4000	MHz
Test Frequency			2140		MHz
Gain		15.5	17.8		dB
Input Return Loss			12		dB
Output Return Loss			10		dB
Output P1dB		+26.4	+27.5		dBm
Output IP3	See Note 1.	+41	+43.8		dBm
WCDMA Pout @ -50 dBc ACLR	See Note 2.		+18.5		dBm
Noise Figure			3.9		dB
V <sub>cc</sub>			5		V
Quiescent Current, I <sub>cq</sub>		115	137	155	mA
Thermal Resistance (jnc to case) θ <sub>jc</sub>				50	°C/W

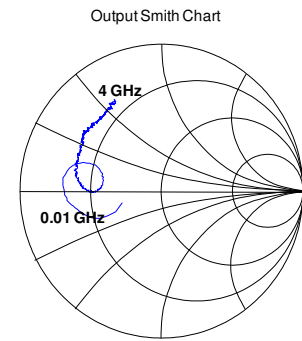
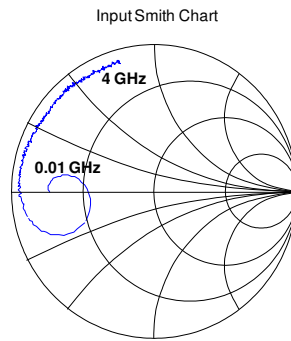
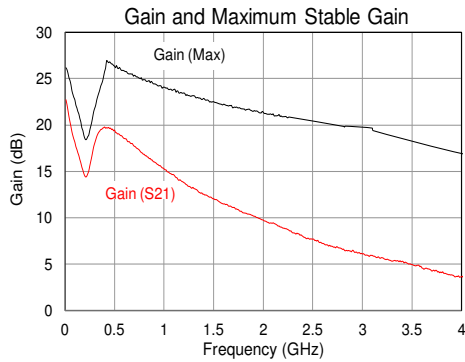
#### Notes

- OIP3 measured with two tones at an output power of +9 dBm / tone separated by 1 MHz. The suppression on the largest IM3 product is used to calculate the OIP3 using 2:1 rule.
- ACLR Test set-up: 3GPP WCDMA, TM1+64 DPCH, +5 MHz offset, PAR = 10.2 dB at 0.01% Prob.

### Device Characterization Data

# TQP7M9102

## 1/2W High Linearity Amplifier



Note: The gain for the unmatched device in 50 ohm system is shown as the trace in red color, [gain (S21)]. For a tuned circuit for a particular frequency, it is expected that actual gain will be higher, up to the maximum stable gain. The maximum stable gain is shown in the black [Gain (MAX)]. The impedance plots are shown from 0.01 – 4 GHz.

### S-Parameter Data

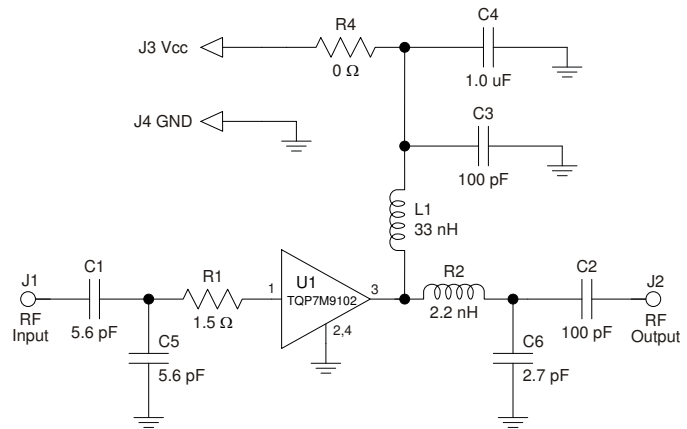
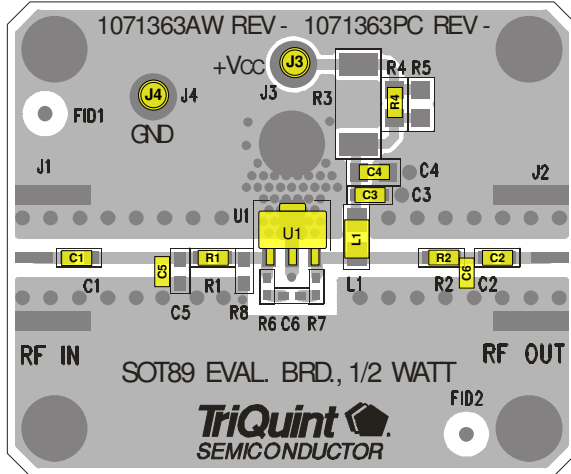
$V_{cc} = +5\text{ V}$ ,  $I_{cq} = 135\text{ mA}$ ,  $T = +25^\circ\text{ C}$ , unmatched 50 ohm system, calibrated to device leads

Freq (MHz)	S11 (dB)	S11 (ang)	S21 (dB)	S21 (ang)	S12 (dB)	S12 (ang)	S22 (dB)	S22 (ang)
50	-2.55	176.64	20.38	156.15	-35.04	-9.37	-5.88	-159.98
100	-2.91	172.21	18.15	151.53	-35.97	-20.12	-4.45	-167.94
200	-5.79	172.18	14.52	160.74	-41.94	-60.14	-3.20	177.62
400	-1.41	-163.37	19.80	154.97	-34.61	49.55	-7.14	165.58
600	-0.52	179.77	18.56	125.67	-33.11	19.10	-6.55	178.58
800	-0.45	171.80	16.85	108.86	-32.96	8.46	-5.41	178.08
1000	-0.49	165.43	15.28	95.36	-32.92	-1.08	-4.76	174.13
1200	-0.60	160.30	13.79	85.52	-33.15	-4.65	-4.38	171.06
1400	-0.60	157.51	12.55	77.70	-33.23	-9.05	-4.24	167.58
1600	-0.67	152.76	11.49	69.57	-33.03	-15.12	-4.15	163.37
1800	-0.74	148.28	10.53	62.39	-32.96	-19.02	-4.00	159.18
2000	-0.72	143.55	9.75	54.69	-33.03	-20.90	-3.89	155.31
2200	-0.78	139.03	8.88	48.56	-32.96	-25.51	-3.77	150.66
2400	-0.71	135.24	7.99	42.25	-32.88	-27.98	-3.40	146.69
2600	-0.74	131.98	7.23	36.47	-33.43	-30.45	-3.38	144.96
2800	-0.75	128.79	6.58	31.19	-33.15	-33.43	-3.44	142.02
3000	-0.80	126.32	6.09	26.41	-33.23	-36.48	-3.50	139.73
3200	-0.75	122.75	5.69	20.73	-33.43	-37.86	-3.39	137.14
3400	-0.81	118.06	5.30	14.38	-33.39	-44.57	-3.48	130.99
3600	-0.82	113.62	4.59	7.77	-33.03	-43.44	-3.34	124.40
3800	-0.71	108.88	4.07	1.73	-32.92	-50.92	-3.04	120.16
4000	-0.68	105.86	3.64	-2.85	-33.15	-54.00	-2.92	118.44

### Application Circuit 869-960 MHz (TQP7M9102-PCB900)

# TQP7M9102

## 1/2W High Linearity Amplifier



### Notes:

1. See PC Board Layout, page 7 for more information.
2. Components shown on the silkscreen but not on the schematic are not used.
3. 0 Ω resistor (R4) may be replaced with copper trace in the target application layout.
4. The recommended component values are dependent upon the frequency of operation.
5. All components are of 0603 size unless stated on the schematic.
6. Critical component placement locations:
  - Distance from U1 Pin 1 (left edge) to C5 (right edge): 255 mils (12.1 deg. at 920 MHz)
  - Distance from U1 Pin 1 (left edge) to C1 (right edge): 460 mils (21.9 deg. at 920 MHz)
  - Distance from U1 Pin 3 (right edge) to R2 (left edge): 290 mils (13.8 deg. at 920 MHz)
  - Distance from U1 Pin 3 (right edge) to C6 (left edge): 370 mils (17.6 deg. at 920 MHz)

## Bill of Material

Ref Des	Value	Description	Manuf.	Part Number
n/a	n/a	Printed Circuit Board	TriQuint	1071363
U1	n/a	TQP7M9102 Amplifier, SOT-89 pkg.	TriQuint	TQP7M9102
R4	0 Ω	Resistor, Chip, 0603, 5%, 1/16W	various	
R1	1.5 Ω	Resistor, Chip, 0603, 5%, 1/16W	various	
R2	2.2 nH	Inductor, 0603, +/-0.3 nH	Toko	LL1608-FSL2N2S
L1	33 nH	Inductor, 0805, 5%, Coilcraft CS Series	Coilcraft	0805CS-330XJLB
C1, C5	5.6 pF	Cap., Chip, 0603, +/-0.1pF. 200V. NPO/COG	AVX	06032U5R6BAT2A
C6	2.7 pF	Cap., Chip, 0603, +/-0.1pF. 200V. NPO/COG	AVX	06032U2R7BAT2A
C2, C3	100 pF	Cap., Chip, 5%, 50V, NPO/COG	various	
C4	1.0 uF	Cap., Chip, 10%, 10V, X5R	various	

# TQP7M9102

## ½W High Linearity Amplifier



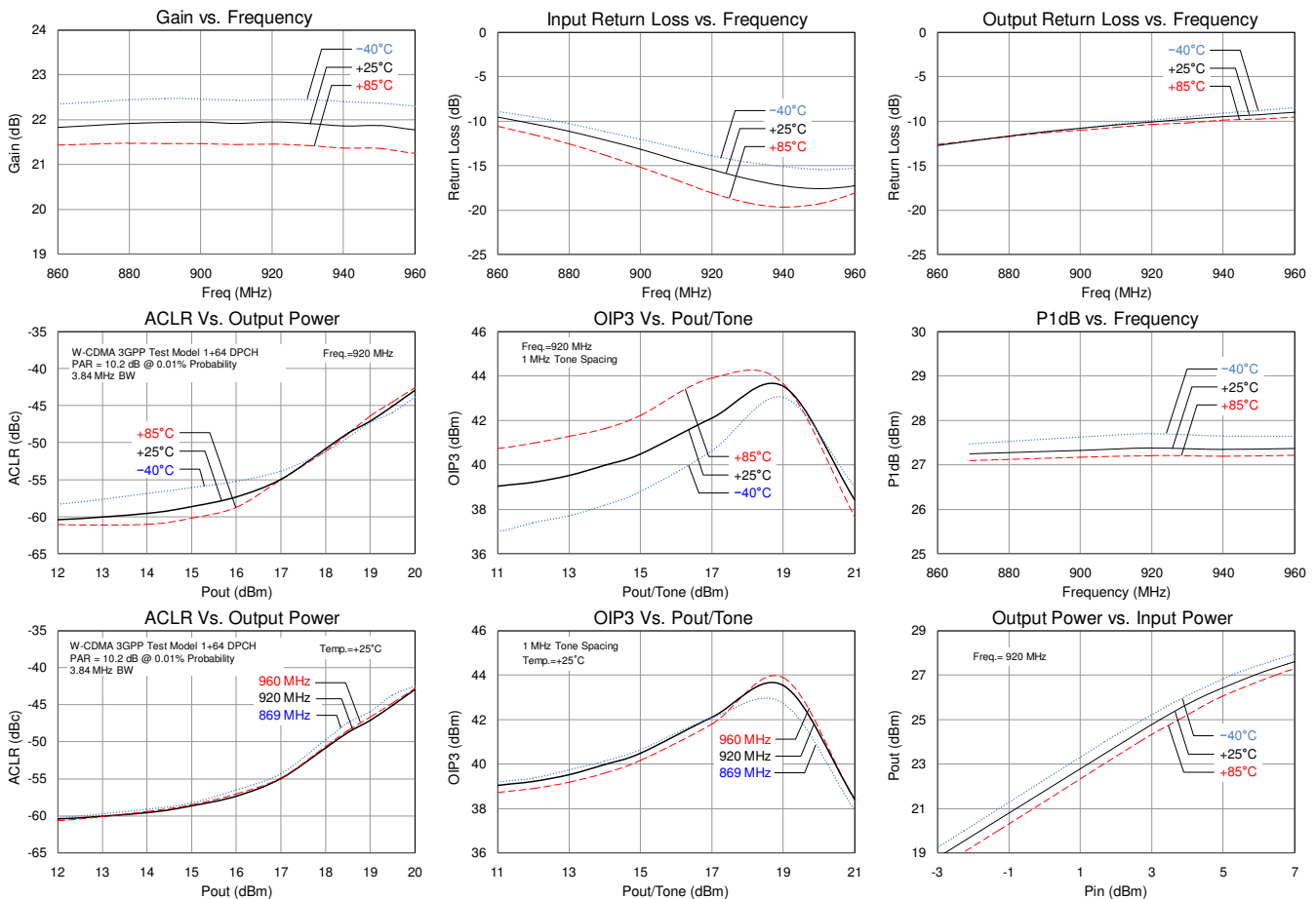
### Typical Performance 869-960 MHz

Frequency	MHz	869	920	960
Gain	dB	21.8	21.9	21.7
Input Return Loss	dB	-10	-16	-17
Output Return Loss	dB	-12	-10	-9
Output P1dB	dBm	+27.3	+27.4	+27.4
Output IP3 (+19 dBm/tone, Δf = 1 MHz)	dBm	+42.7	+43.4	+43.9
WCDMA Channel Power (at -50 dBc ACLR) [1]	dBm	+18.0	+18.2	+18.1
Noise Figure	dB	5.9	5.9	5.9
Supply Voltage, Vcc	V	+5		
Quiescent Collector Current, Icq	mA	137		

Notes:

1. ACLR Test set-up: 3GPP WCDMA, TM1+64 DPCH, +5 MHz offset, PAR = 10.2 dB at 0.01% Prob.

### RF Performance Plots 869-960 MHz

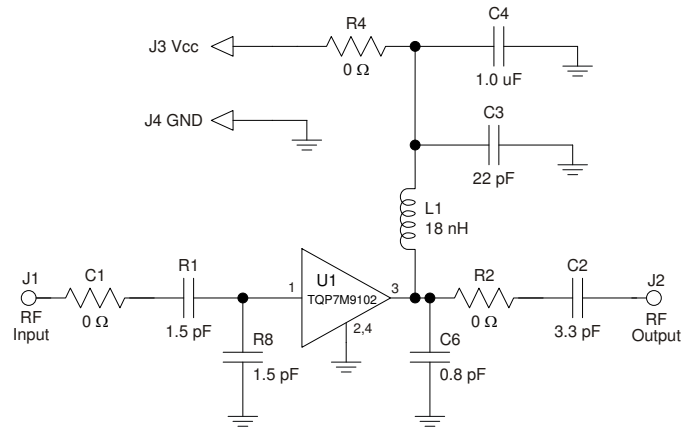
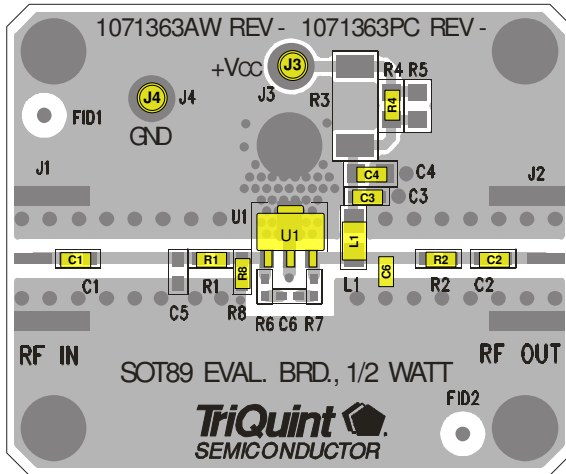


# TQP7M9102

## 1/2W High Linearity Amplifier



### Application Circuit 2110-2170 MHz (TQP7M9102-PCB2140)



#### Notes:

1. See PC Board Layout, page 7 for more information.
2. Components shown on the silkscreen but not on the schematic are not used.
3. 0 Ω resistors (C1, R2) may be replaced with copper trace in the target application layout.
4. The recommended component values are dependent upon the frequency of operation.
5. All components are of 0603 size unless stated on the schematic.
6. Critical component placement locations:
  - Distance from U1 Pin 1 (left edge) to R8 (right edge): 40 mils (4.4 deg. at 2140 MHz)
  - Distance from U1 Pin 1 (left edge) to R1 (right edge): 115 mils (12.7 deg. at 2140 MHz)
  - Distance from U1 Pin 3 (right edge) to C6 (left edge): 180 mils (19.9 deg. at 2140 MHz)
  - Distance from U1 Pin 3 (right edge) to C2 (left edge): 450 mils (49.8 deg. at 2140 MHz)

### Bill of Material

Ref Des	Value	Description	Manuf.	Part Number
n/a	n/a	Printed Circuit Board	TriQuint	1071363
U1	n/a	TQP7M9102 Amplifier, SOT-89 pkg.	TriQuint	TQP7M9102
C1, R2, R4	0 Ω	Resistor, Chip, 0603, 5%, 1/16W	various	
L1	18 nH	Inductor, 0805, Coilcraft CS Series	Coilcraft	0805CS-180XJLB
R1, R8	1.5 pF	Cap., Chip, 0603, +/-0.1pF. 200V. NPO/COG	AVX	06032U1R5BAT2A
C2	3.3 pF	Cap., Chip, 0603, +/-0.1pF. 200V NPO/COG	AVX	06032U3R3BAT2A
C3	22 pF	Cap., Chip, 5%, 50V, NPO/COG	various	
C4	1.0 uF	Cap., Chip, 10%, 10V, X5R	various	
C6	0.8 pF	Cap., Chip, 0603, +/-0.1pF. 200V NPO/COG	AVX	06032U0R8BAT2A

# TQP7M9102

## 1/2W High Linearity Amplifier



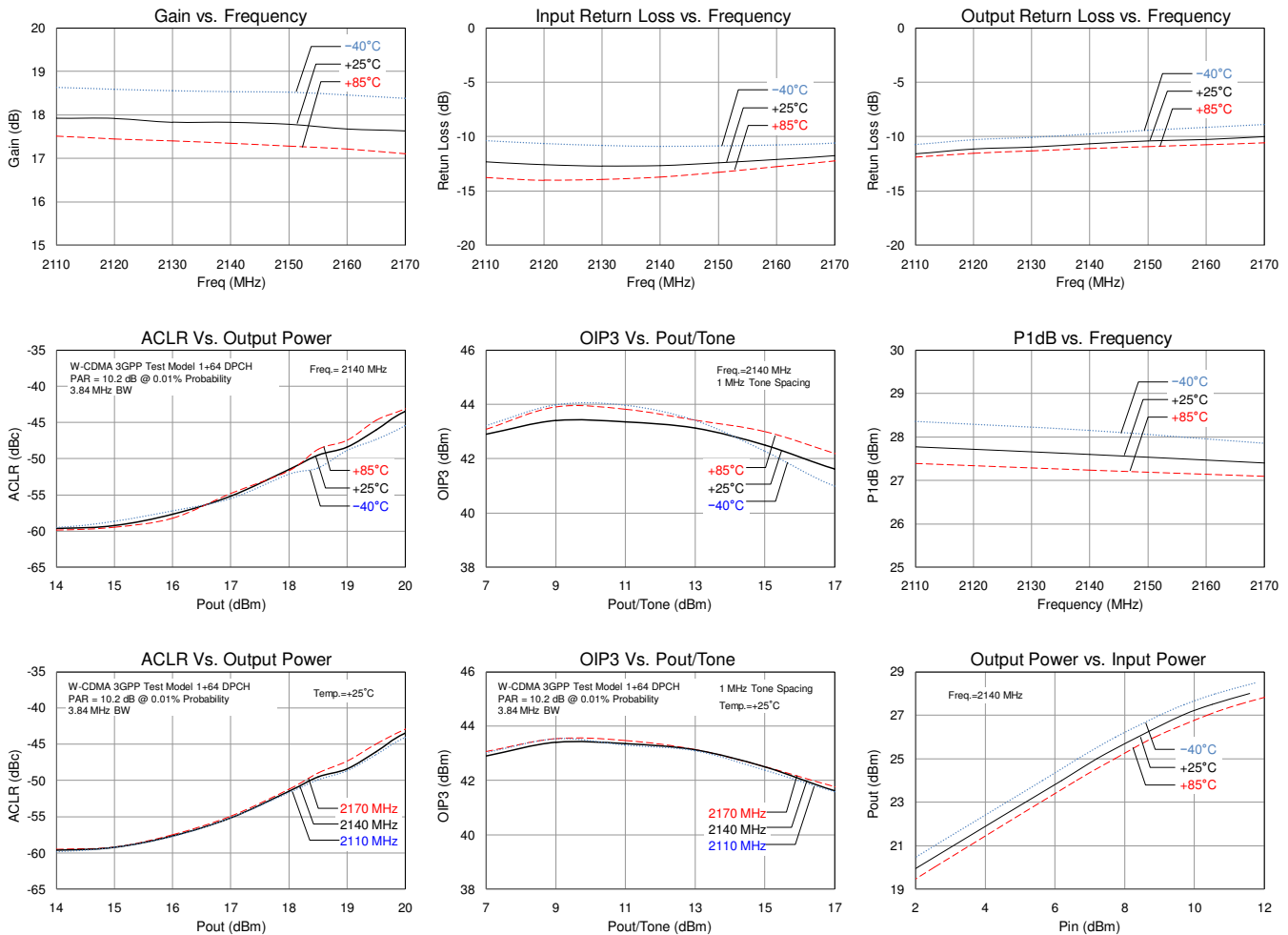
### Typical Performance 2110-2170 MHz

Frequency	MHz	2110	2140	2170
Gain	dB	17.9	17.8	17.7
Input Return Loss	dB	-12	-12	-11
Output Return Loss	dB	-12	-11	-10
Output P1dB	dBm	+27.8	+27.6	+27.4
Output IP3 (+9 dBm/tone, Δf = 1 MHz)	dBm	+43.6	+43.5	+43.6
WCDMA Channel Power (at -50 dBc ACLR) [1]	dBm	+18.5	+18.4	+18.3
Noise Figure	dB	3.8	3.9	4.0
Supply Voltage, Vcc	V	5		
Quiescent Collector Current, Icq	mA	137		

Notes:

1. ACLR Test set-up: 3GPP WCDMA, TM1+64 DPCH, +5 MHz offset, PAR = 10.2 dB at 0.01% Prob.

### RF Performance Plots 2110-2170 MHz

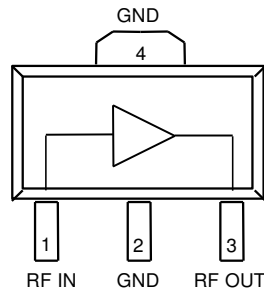


# TQP7M9102

## 1/2W High Linearity Amplifier



### Pin Configuration and Description



Pin	Symbol	Description
1	RF IN	RF Input. Requires external match for optimal performance. External DC Block required.
2, 4	GND	RF/DC Ground Connection
3	RFout / Vcc	RF Output. Requires external match for optimal performance. External DC Block and supply voltage is required.

### Applications Information

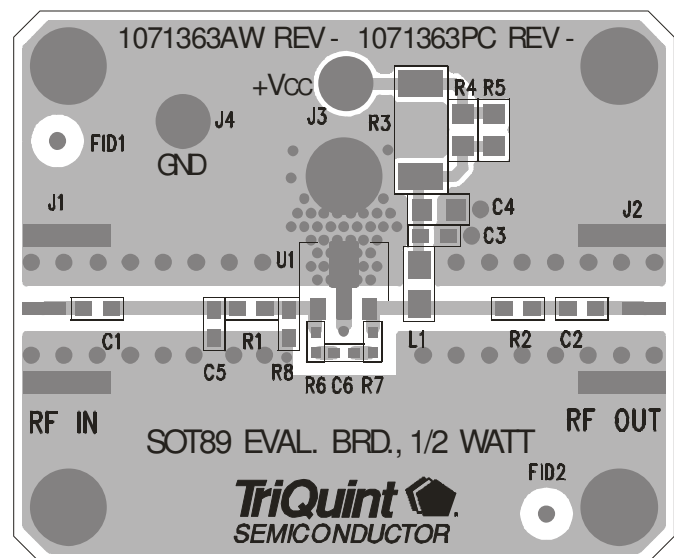
#### PC Board Layout

PCB Material (stackup):

- 1 oz. Cu top layer
- 0.014 inch Nelco N-4000-13,  $\epsilon_r=3.7$
- 1 oz. Cu MIDDLE layer 1
- Core Nelco N-4000-13
- 1 oz. Cu middle layer 2
- 0.014 inch Nelco N-4000-13
- 1 oz. Cu bottom layer
- Finished board thickness is 0.062±.006

50 ohm line dimensions: width = .031", spacing = .035".

The pad pattern shown has been developed and tested for optimized assembly at TriQuint Semiconductor. The PCB land pattern has been developed to accommodate lead and package tolerances. Since surface mount processes vary from supplier to supplier, careful process development is





# TQP7M9102

## 1/2W High Linearity Amplifier



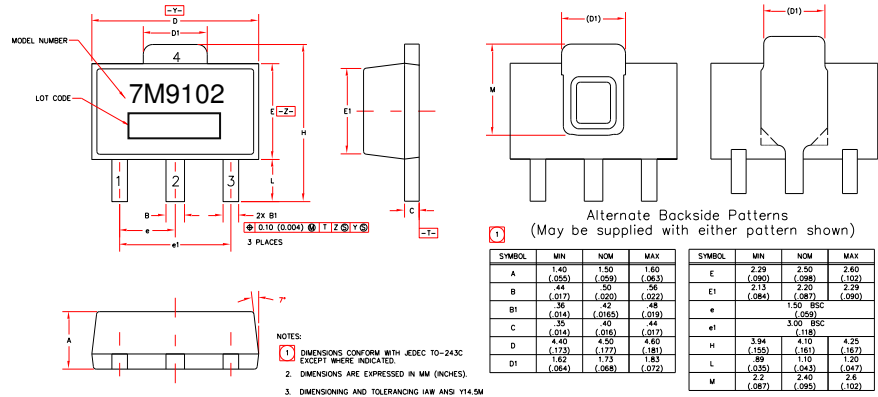
recommended.

### Mechanical Information

#### Package Information and Dimensions

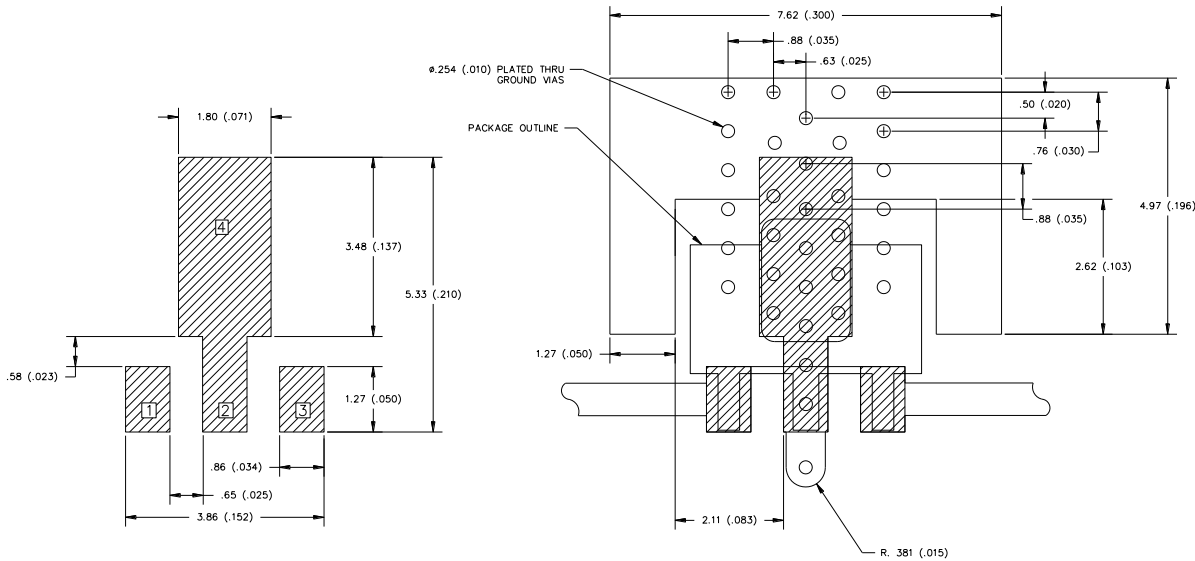
This package is lead-free/RoHS-compliant. The plating material on the leads is NiPdAu. It is compatible with both lead-free (maximum 260 °C reflow temperature) and lead (maximum 245 °C reflow temperature) soldering processes.

The component will be marked with a “7M9102” designator with an alphanumeric lot code on the top surface of package.



#### Mounting Configuration

All dimensions are in millimeters (inches). Angles are in degrees.



Notes:

- Ground / thermal vias are critical for the proper performance of this device. Vias should use a .35mm (#80 / .0135”) diameter drill and have a final plated thru diameter of .25 mm (.010”).
- Add as much copper as possible to inner and outer layers near the part to ensure optimal thermal performance.
- RF trace width depends upon the PC board material and construction.
- Use 1 oz. Copper minimum.

# TQP7M9102

## ½W High Linearity Amplifier



### Product Compliance Information

#### ESD Information



#### Caution! ESD-Sensitive Device

ESD Rating: Class 2  
Value:  $\geq 2000$  V and  $< 4000$  V  
Test: Human Body Model (HBM)  
Standard: JEDEC Standard JESD22-A114

ESD Rating: Class IV  
Value:  $>2000$  V  
Test: Charged Device Model (CDM)  
Standard: JEDEC Standard JESD22-C101

#### MSL Rating

Level 3 at +260 °C convection reflow  
The part is rated Moisture Sensitivity Level 3 at 260°C per JEDEC standard IPC/JEDEC J-STD-020.

#### Solderability

Compatible with the latest version of J-STD-020, Lead free solder, 260°

This part is compliant with EU 2002/95/EC RoHS directive (Restrictions on the Use of Certain Hazardous Substances in Electrical and Electronic Equipment).

This product also has the following attributes:

- Lead Free
- Halogen Free (Chlorine, Bromine)
- Antimony Free
- TBBP-A (C<sub>15</sub>H<sub>12</sub>Br<sub>4</sub>O<sub>2</sub>) Free
- PFOS Free
- SVHC Free

### Contact Information

For the latest specifications, additional product information, worldwide sales and distribution locations, and information about TriQuint:

Web: [www.triquint.com](http://www.triquint.com)  
Email: [info-sales@tqs.com](mailto:info-sales@tqs.com)

Tel: +1.503.615.9000  
Fax: +1.503.615.8902

For technical questions and application information:

Email: [sjapplications.engineering@tqs.com](mailto:sjapplications.engineering@tqs.com)

### Important Notice

The information contained herein is believed to be reliable. TriQuint makes no warranties regarding the information contained herein. TriQuint assumes no responsibility or liability whatsoever for any of the information contained herein. TriQuint assumes no responsibility or liability whatsoever for the use of the information contained herein. The information contained herein is provided "AS IS, WHERE IS" and with all faults, and the entire risk associated with such information is entirely with the user. All information contained herein is subject to change without notice. Customers should obtain and verify the latest relevant information before placing orders for TriQuint products. The information contained herein or any use of such information does not grant, explicitly or implicitly, to any party any patent rights, licenses, or any other intellectual property rights, whether with regard to such information itself or anything described by such information.

TriQuint products are not warranted or authorized for use as critical components in medical, life-saving, or life-sustaining applications, or other applications where a failure would reasonably be expected to cause severe personal injury or death.